

METHOD FOR PACKING ELECTRONIC DEVICE BY
INTERCONNECTING FRAME BODY AND FRAME LEADS WITH
INSULATING BLOCK AND ITS PACKING STRUCTURE

5 ABSTRACT OF THE DISCLOSURE

A packing structure of an electronic device by interconnecting a frame and frame leads with an insulating block is provided. The packing structure has the advantage of measuring the electrical characteristics of the semi-product before being subject to a plastic
10 molding. The packing structure includes a frame having a package area where an electronic device is disposed, an insulating block disposed on one side of the package area and connected to the frame, and a plurality of frame leads aligned in parallel and connected to the insulating block and the electronic device.